

HIGH SIDE SMART POWER SOLID STATE RELAY

Table 1. General Features

Type	V _{DSS}	R _{DS(on)}	I _{OUT}	V _{CC}
VN02NSP VN02NPT	60 V	0.4 Ω	6 A	26 V

- OUTPUT CURRENT (CONTINUOUS):
6A @ T_C=25°C
- 5V LOGIC LEVEL COMPATIBLE INPUT
- THERMAL SHUT-DOWN
- UNDER VOLTAGE SHUT-DOWN
- OPEN DRAIN DIAGNOSTIC OUTPUT
- VERY LOW STAND-BY POWER
DISSIPATION

DESCRIPTION

The VN02NSP/VN02NPT are monolithic devices made using STMicroelectronics VIPower Technology, intended for driving resistive or inductive loads with one side grounded.

Built-in thermal shut-down protects the chip from over temperature and short circuit.

The input control is 5V logic level compatible.

The open drain diagnostic output indicates open circuit (no load) and over temperature status.

Figure 1. Package

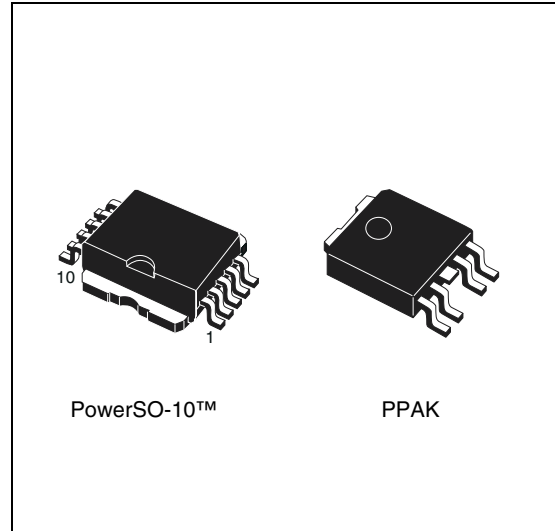


Table 2. Order Codes

Package	Tube	Tape and Reel
PowerSO-10	VN02NSP	VN02NSP13TR
PPAK	VN02NPT	VN02NPT13TR

Figure 2. Block Diagram

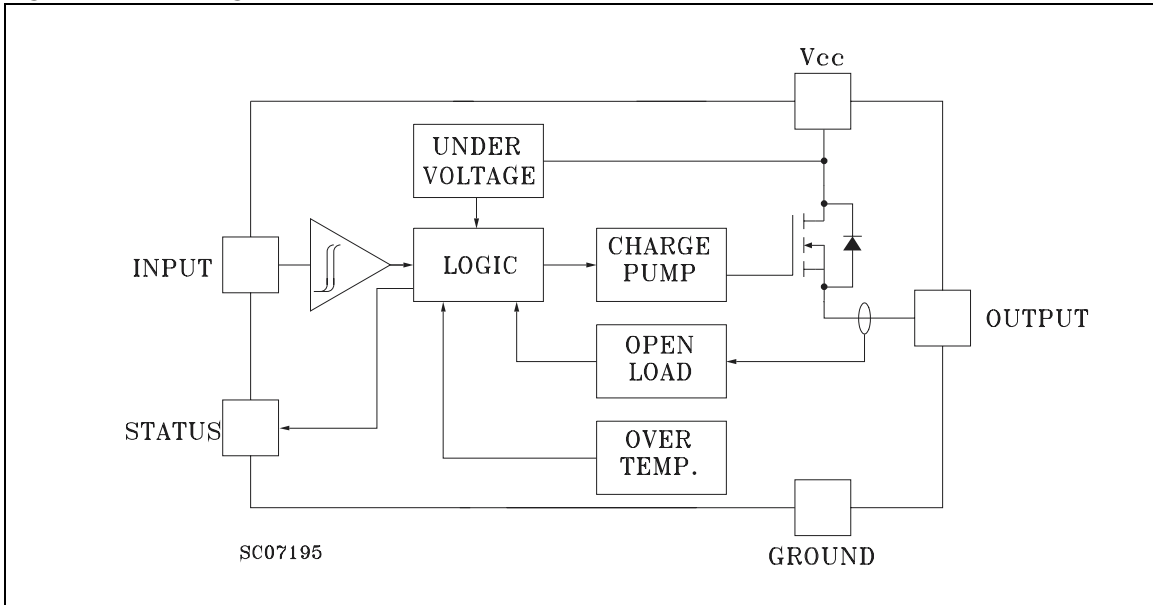


Table 3. Absolute Maximum Ratings

Symbol	Parameter	Value		Unit
		PowerSO-10	PPAK	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	60		V
I_{OUT}	Output Current (cont.)	6		A
I_R	Reverse Output Current	-6		A
I_{IN}	Input Current	± 10		mA
$-V_{CC}$	Reverse Supply Voltage	-4		V
I_{STAT}	Status Current	± 10		mA
V_{ESD}	Electrostatic Discharge (1.5 k Ω , 100 pF)	2000		V
P_{tot}	Power Dissipation at $T_c \leq 25^\circ\text{C}$	58	46	W
T_j	Junction Operating Temperature	-40 to 150		$^\circ\text{C}$
T_{stg}	Storage Temperature	-55 to 150		$^\circ\text{C}$

Figure 3. Connection Diagrams

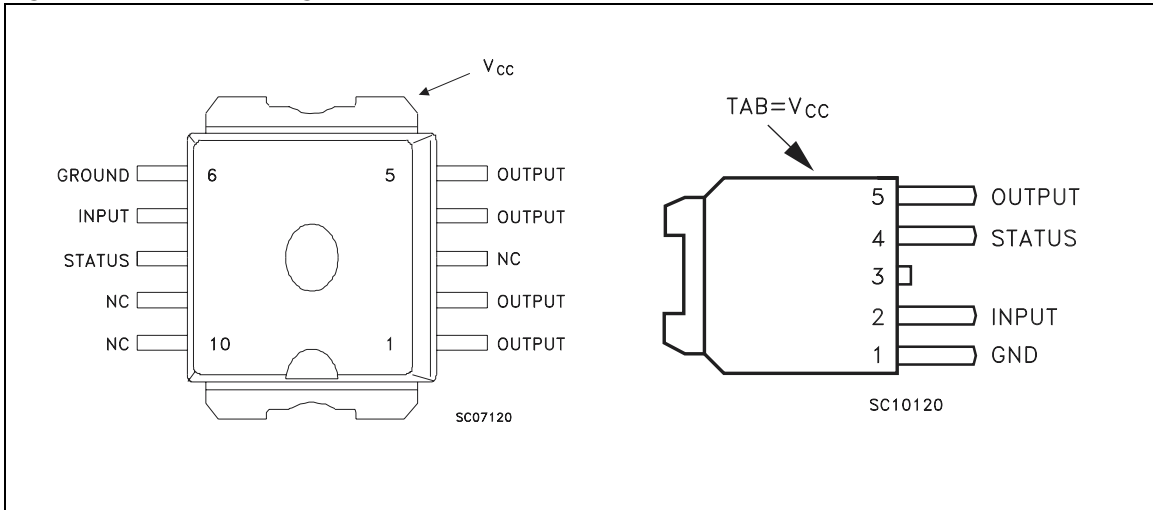


Figure 4. Current and Voltage Conventions

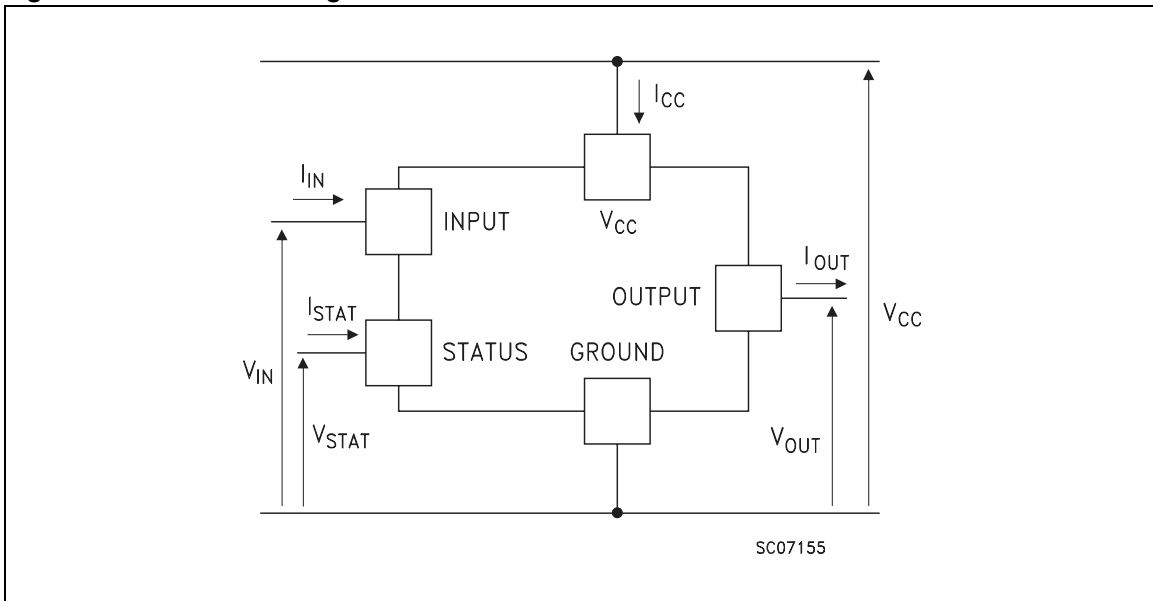


Table 4. Thermal Data

Symbol	Parameter	Max	Value		Unit
			PowerSO-10	PPAK	
$R_{thj-case}$	Thermal Resistance Junction-case	Max	2.14	3.33	°C/W
$R_{thj-amb}$	Thermal Resistance Junction-ambient ⁽¹⁾	Max	62.5	100	°C/W

Note: 1. When mounted using minimum recommended pad size on FR-4 board.

ELECTRICAL CHARACTERISTICS

 ($V_{CC} = 13\text{ V}$; $-40 \leq T_j \leq 125\text{ °C}$ unless otherwise specified)

Table 5. Power

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_{CC}	Supply Voltage		7		26	V
R_{on}	On State Resistance	$I_{OUT} = 3\text{ A}$ $I_{OUT} = 3\text{ A}$; $T_j = 25\text{ °C}$			0.8 0.4	Ω Ω
I_S	Supply Current	Off State; $T_j \geq 25\text{ °C}$ On State			50 15	μA mA

Table 6. Switching

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on Delay Time Of Output Current	$I_{OUT} = 3\text{ A}$; Resistive Load Input Rise Time $< 0.1\ \mu\text{s}$; $T_j = 25\text{ °C}$		10		μs
t_r	Rise Time Of Output Current	$I_{OUT} = 3\text{ A}$; Resistive Load Input Rise Time $< 0.1\ \mu\text{s}$; $T_j = 25\text{ °C}$		15		μs
$t_{d(off)}$	Turn-off Delay Time Of Output Current	$I_{OUT} = 3\text{ A}$; Resistive Load Input Rise Time $< 0.1\ \mu\text{s}$; $T_j = 25\text{ °C}$		15		μs
t_f	Fall Time Of Output Current	$I_{OUT} = 3\text{ A}$; Resistive Load Input Rise Time $< 0.1\ \mu\text{s}$; $T_j = 25\text{ °C}$		6		μs
$(di/dt)_{on}$	Turn-on Current Slope	$I_{OUT} = 3\text{ A}$ $I_{OUT} = I_{OV}$			0.5 2	$\text{A}/\mu\text{s}$ $\text{A}/\mu\text{s}$
$(di/dt)_{off}$	Turn-off Current Slope	$I_{OUT} = 3\text{ A}$ $I_{OUT} = I_{OV}$			2 4	$\text{A}/\mu\text{s}$ $\text{A}/\mu\text{s}$

Table 7. Logic Input

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_{IL}	Input Low Level Voltage				0.8	V
V_{IH}	Input High Level Voltage		2		Note 2	V
$V_{I(hyst)}$	Input Hysteresis Voltage			0.5		V
I_{IN}	Input Current	$V_{IN} = 5\text{ V}$		250	500	μA
V_{ICL}	Input Clamp Voltage	$I_{IN} = 10\text{ mA}$ $I_{IN} = -10\text{ mA}$		6 -0.7		V V

Note: 2. The V_{IH} is internally clamped at 6V about. It is possible to connect this pin to an higher voltage via an external resistor calculated to not exceed 10 mA at the input pin.

ELECTRICAL CHARACTERISTICS (cont'd)

Table 8. Protections and Diagnostics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{STAT}^{(3)}$	Status Voltage Output Low	$I_{STAT} = 1.6 \text{ mA}$			0.4	V
V_{USD}	Under Voltage Shut Down			6.5		V
$V_{SCL}^{(3)}$	Status Clamp Voltage	$I_{STAT} = 10 \text{ mA}$ $I_{STAT} = -10 \text{ mA}$		6 -0.7		V V
t_{sc}	Switch-off Time in Short Circuit Condition at Start-Up	$R_{LOAD} < 10 \text{ m}\Omega$; $T_c = 25 \text{ }^\circ\text{C}$		1.5	5	ms
I_{OV}	Over Current	$R_{LOAD} < 10 \text{ m}\Omega$; $-40 \leq T_c \leq 125 \text{ }^\circ\text{C}$			28	A
I_{AV}	Average Current in Short Circuit	$R_{LOAD} < 10 \text{ m}\Omega$; $T_c = 85 \text{ }^\circ\text{C}$		0.9		A
I_{OL}	Open Load Current Level		5		70	mA
T_{TSD}	Thermal Shut-down Temperature		140			$^\circ\text{C}$
T_R	Reset Temperature		125			$^\circ\text{C}$

Note: 3. Status determination > 100 ms after the switching edge.

FUNCTIONAL DESCRIPTION

The device has a diagnostic output which indicates open circuit (no load) and over temperature conditions. The output signals are processed by internal logic.

To protect the device against short circuit and over-current condition, the thermal protection turns the integrated Power MOS off at a minimum junction temperature of $140 \text{ }^\circ\text{C}$. When the temperature returns to about $125 \text{ }^\circ\text{C}$ the switch is automatically turned on again.

In short circuit conditions the protection reacts with virtually no delay, the sensor being located in the region of the die where the heat is generated.

PROTECTING THE DEVICE AGAINST REVERSE BATTERY

The simplest way to protect the device against a continuous reverse battery voltage (-26V) is to insert a Schottky diode between pin 1 (GND) and ground, as shown in the typical application circuit (Figure 7).

The consequences of the voltage drop across this diode are as follows:

- If the input is pulled to power GND, a negative voltage of $-V_F$ is seen by the device. (V_{IL} , V_{IH} thresholds and V_{STAT} are increased by V_F with respect to power GND).
- The undervoltage shutdown level is increased by V_F .

If there is no need for the control unit to handle external analog signals referred to the power GND, the best approach is to connect the reference potential of the control unit to node (1) (see application circuit in Figure 8), which becomes the common signal GND for the whole control board.

In this way no shift of V_{IH} , V_{IL} and V_{STAT} takes place and no negative voltage appears on the INPUT pin; this solution allows the use of a standard diode, with a breakdown voltage able to handle any ISO normalized negative pulses that occurs in the automotive environment.

Table 9. Truth Table

	Input	Output	Diagnostic
Normal Operation	L	L	H
	H	H	H
Open Circuit (No Load)	H	H	L
Over-temperature	H	L	L
Under-voltage	X	L	H

Figure 5. Waveforms

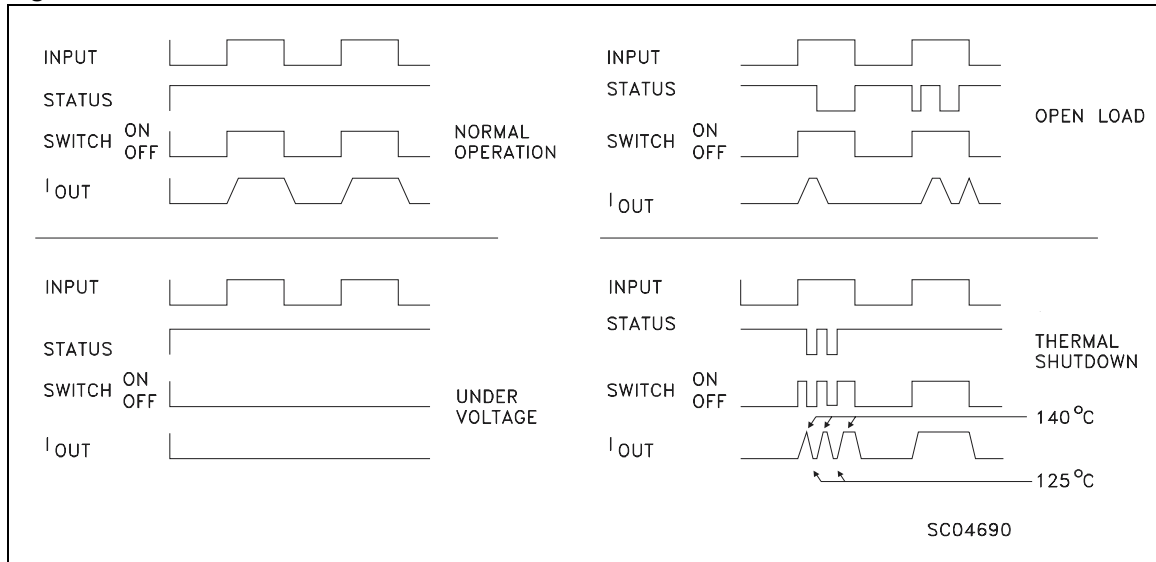


Figure 6. Over Current Test Circuit

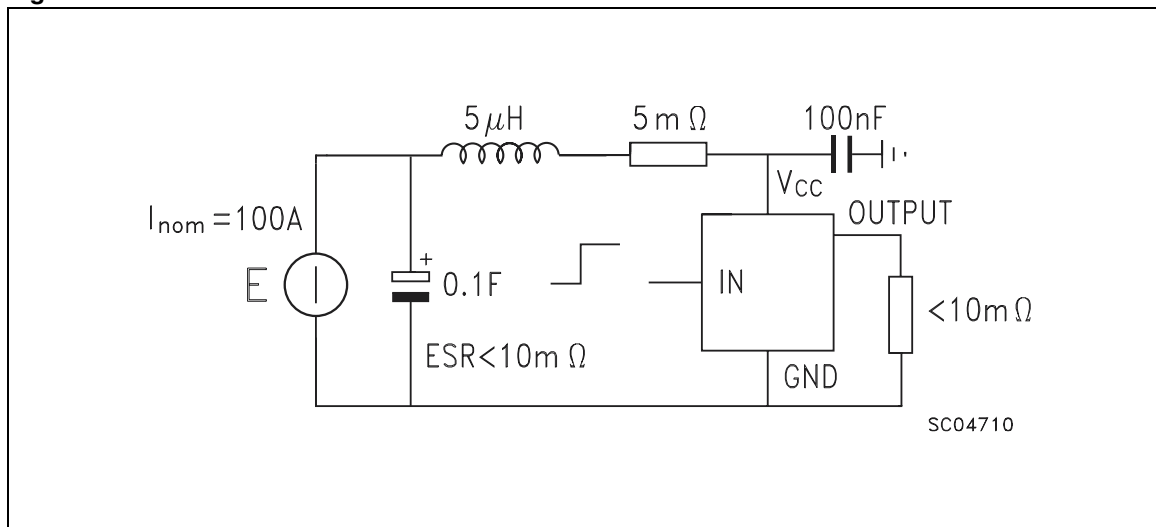


Figure 7. Typical Application Circuit With A Schottky Diode For Reverse Supply Protection

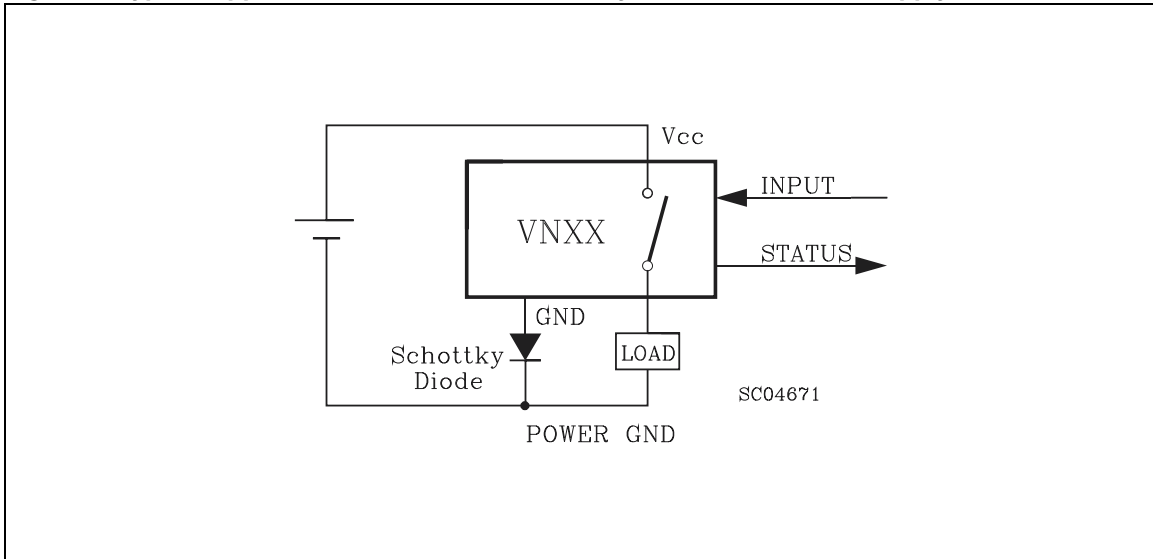


Figure 8. Typical Application Circuit With Separate Signal Ground

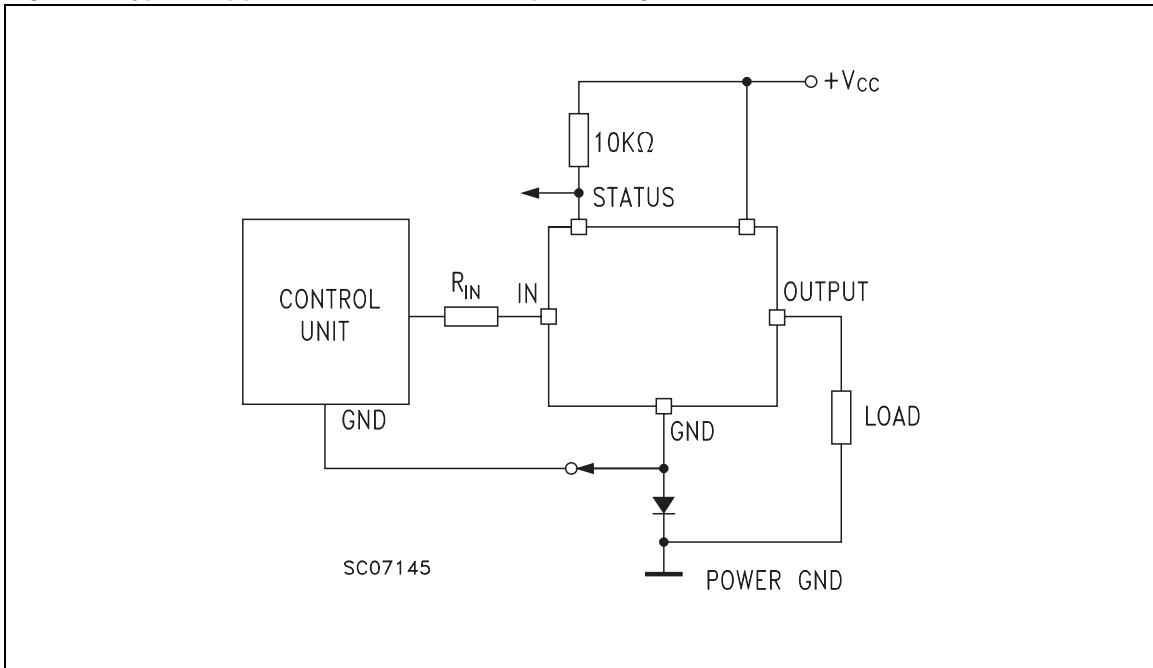


Figure 9. $R_{DS(on)}$ vs Junction Temperature

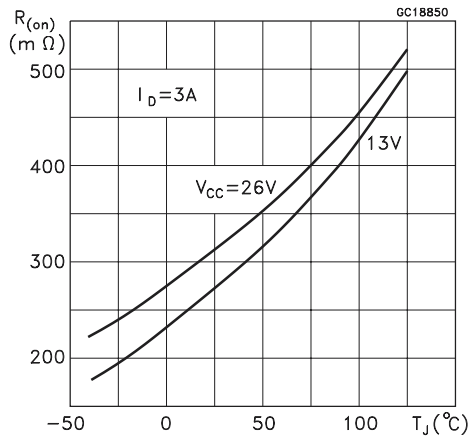


Figure 10. $R_{DS(on)}$ vs Supply Voltage

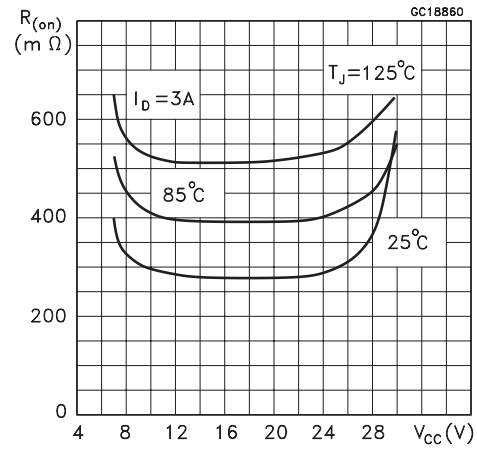


Figure 11. $R_{DS(on)}$ vs Output Current

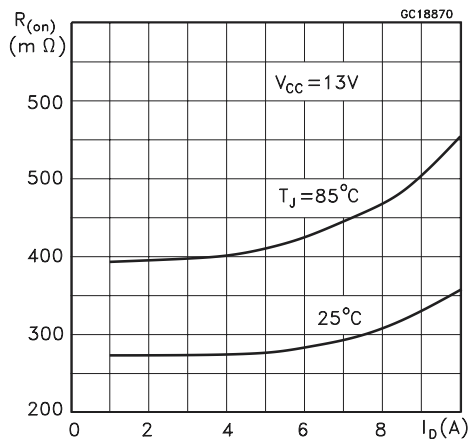


Figure 12. Input voltages vs Junction Temperature

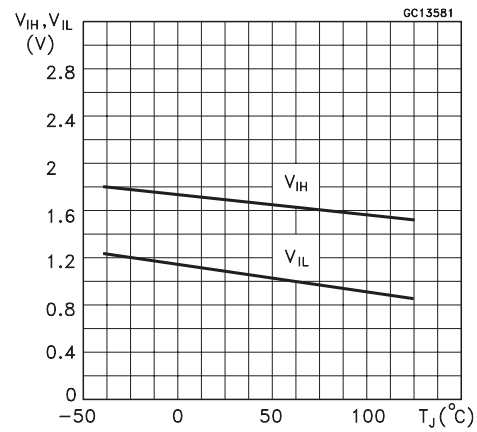


Figure 13. Output Current Derating

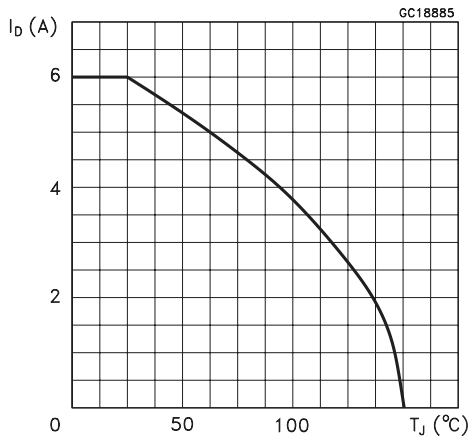
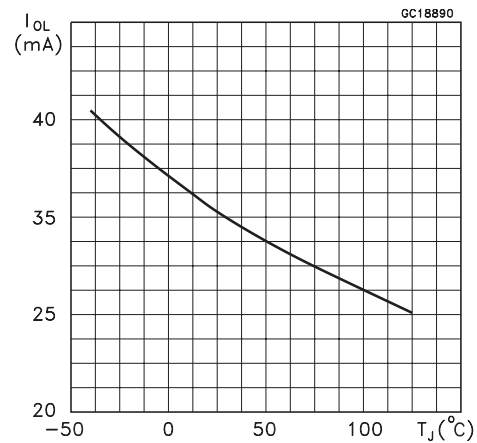


Figure 14. Open Load vs Junction Temperature

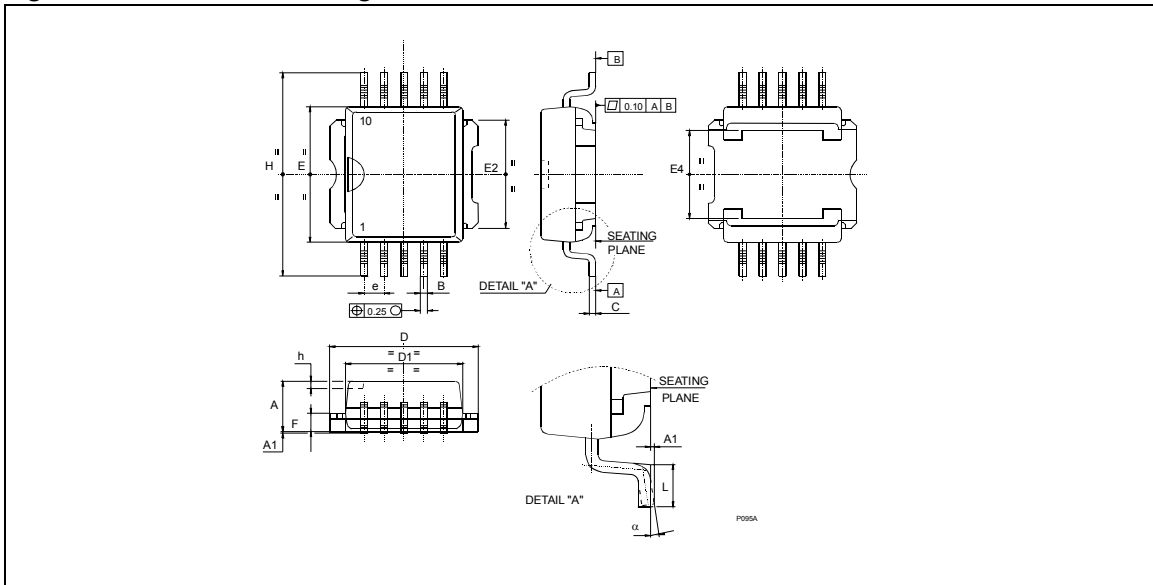


PACKAGE MECHANICAL

Table 10. PowerSO-10 Mechanical Data

Symbol	millimeters		
	Min	Typ	Max
A	3.35		3.65
A (*)	3.4		3.6
A1	0.00		0.10
B	0.40		0.60
B (*)	0.37		0.53
C	0.35		0.55
C (*)	0.23		0.32
D	9.40		9.60
D1	7.40		7.60
E	9.30		9.50
E2	7.20		7.60
E2 (*)	7.30		7.50
E4	5.90		6.10
E4 (*)	5.90		6.30
e		1.27	
F	1.25		1.35
F (*)	1.20		1.40
H	13.80		14.40
H (*)	13.85		14.35
h		0.50	
L	1.20		1.80
L (*)	0.80		1.10
a	0°		8°
α (*)	2°		8°

Figure 15. PowerSO-10 Package Dimensions



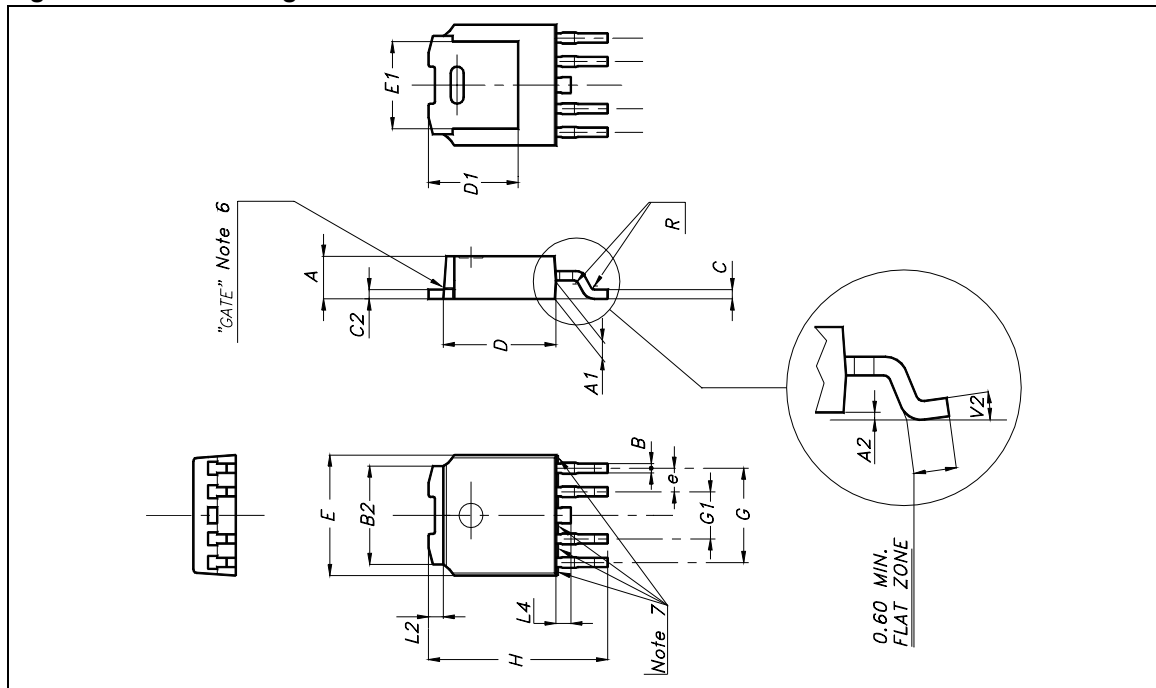
Note: Drawing is not to scale.

VN02NSP/VN02NPT

Table 11. PPAK Mechanical Data

Symbol	millimeters		
	Min	Typ	Max
A	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
B	0.40		0.60
B2	5.20		5.40
C	0.45		0.60
C2	0.48		0.60
D1		5.1	
D	6.00		6.20
E	6.40		6.60
E1		4.7	
e		1.27	
G	4.90		5.25
G1	2.38		2.70
H	9.35		10.10
L2		0.8	1.00
L4	0.60		1.00
R		0.2	
V2	0°		8°
Package Weight		Gr. 0.3	

Figure 16. PPAK Package Dimensions



Note: Drawing is not to scale.

REVISION HISTORY**Table 12. Revision History**

Date	Revision	Description of Changes
September-1997	1	First Issue
18-June-2004	2	Stylesheet update. No content change.

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